



## Product/Process Change Notice - PCN 10\_0133 Rev. A

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This notice is to inform you of a change that will be made to certain ADI products (see Material Report). Any issues with this PCN or requirements to qualify the change (additional data or samples) must be sent to ADI within 30 days of publication date. ADI contact information is listed below.

*Note: Revised fields are indicated by a red field name. See Appendix B for revision history.*

**PCN Title:** AD8541, AD8542, and AD8544 Die Revision, limited BOM Changes to Halide Free, and limited Assembly Site changes to ASE Shanghai.

**Publication Date:** 18-Jul-2011

**Effectivity Date:** 16-Oct-2011 *(the earliest date that a customer could expect to receive changed material)*

### Revision Description:

Including reference to Assembly Site change to ASE for MSOP & SOIC packages. Updates to qualification status and Assembly site changes. Removal of Pb models, as they have converted to obsolete status.

### Description Of Change

See attached table for list of changes by model.

#### Die Changes:

For all 3 products, there were minor changes to the layout of the input stage to improve the input Vos. Those changes affected Poly / Metal 1 / Contact mask layers.

Package BOM: Only PB Free models affected.

#### AD8541

5-SC70: Ablestik 8006NS / Hitachi CEL-8240HF10LX

5-SOT23: QMI519 / CEL-8240HF10LX

8-SOIC: Hitachi EN-4900GC / Hitachi CEL-9240HF10AK

#### AD8542

8-MSOP: Hitachi EN-4900GC / Hitachi CEL-9240HF10AK

8-SOIC: Hitachi EN-4900GC / Hitachi CEL-9240HF10AK

8-TSSOP: Ablestik 84-1LMISR4 / Sumitomo 7351LS (No change - Halide Based)

#### AD8544

14-SOIC: Hitachi EN-4900GC / Hitachi CEL-9240HF10AK

14-TSSOP: Hitachi EN-4900GC / Hitachi CEL-9200HF10

#### REV A:

Including Reference to Assembly site change for SOIC and MSOP packages to ASE-Shanghai Facility. Removal of Pb Models from PCN (Pb moving to lifetime buy status)

### Reason For Change

To improve the manufacturing, planning and delivery with consistent yields, the input layout stage was revised.

The Halide Free migration is in accordance to ADI's manufacturing conversion process, and can be referenced in PCNs 10\_0004 / 10\_0005 / 10\_0006 / 10\_0009. This PCN will supercede in reference to the AD8541/AD8542/AD8544. The 8ld-TSSOP will be converted to Halide Free at a later date.

#### REV A:

The ASE - Shanghai assembly site qualification and conversion is in accordance with PCN 10\_0073, which covers the MSOP, NSOIC, PDIP packages. Not all product models change assembly site. See attached Detailed Change Description.

### Impact of the change (positive or negative) on fit, form, function & reliability

Positive impact to the products function and performance. No impact to fit, form or reliability.

**Product Identification** (this section will describe how to identify the changed material)

There are no changes to product identification markings. Date code tracking is being used to track conversion dates.

**Summary of Supporting Information**

Qualification has been performed per ADI0012, Procedure for Qualification of New or Revised Processes. See attached Qualification Report Summary.

**Comments**

Qualification status reports are provided. Reliability reports, once completed, will be available upon request.

**Supporting Documents**

**Attachment 1: Type:** Qualification Report Summary  
ADI\_PCN\_10\_0133\_Rev\_A\_RQR05994.pdf

**Attachment 2: Type:** Qualification Report Summary  
ADI\_PCN\_10\_0133\_Rev\_A\_AD8541 qualification summary.pdf

**Attachment 3: Type:** Qualification Report Summary  
ADI\_PCN\_10\_0133\_Rev\_A\_AD8544 qualification summary.pdf

**Attachment 4: Type:** Detailed Change Description  
ADI\_PCN\_10\_0133\_Rev\_A\_AD854x BOM Assembly site changes.xls

**For questions on this PCN, send email to the regional contacts below or contact your local ADI sales representative**

**Americas:** PCN\_Americas@analog.com      **Europe:** PCN\_Europe@analog.com      **Japan:** PCN\_Japan@analog.com  
**Rest of Asia:** PCN\_ROA@analog.com

**Appendix A - Affected ADI Models**

**Existing Parts - Product Family / Model Number (20)**

AD8541 / AD8541AKSZ-R2	AD8541 / AD8541AKSZ-REEL7	AD8541 / AD8541ARTZ-R2	AD8541 / AD8541ARTZ-REEL	AD8541 / AD8541ARTZ-REEL7
AD8541 / AD8541ARZ	AD8541 / AD8541ARZ-REEL	AD8541 / AD8541ARZ-REEL7	AD8542 / AD8542ARMZ	AD8542 / AD8542ARMZ-REEL
AD8542 / AD8542ARUZ	AD8542 / AD8542ARUZ-REEL	AD8542 / AD8542ARZ	AD8542 / AD8542ARZ-REEL	AD8542 / AD8542ARZ-REEL7
AD8544 / AD8544ARUZ	AD8544 / AD8544ARUZ-REEL	AD8544 / AD8544ARZ	AD8544 / AD8544ARZ-REEL	AD8544 / AD8544ARZ-REEL7

**Removed Parts On All Revisions - Product Family / Model Number (11)**

AD8541 / AD8541ART-REEL7	AD8542 / AD8542AR	AD8542 / AD8542AR-REEL	AD8542 / AD8542AR-REEL7	AD8542 / AD8542ARM-REEL
AD8542 / AD8542ARU-REEL	AD8544 / AD8544AR	AD8544 / AD8544AR-REEL	AD8544 / AD8544AR-REEL7	AD8544 / AD8544ARU
AD8544 / AD8544ARU-REEL				

**Appendix B - Revision History**

Rev	Publish Date	Rev Description
Rev. -	06-Apr-2011	Initial Release
Rev. A	18-Jul-2011	Including reference to Assembly Site change to ASE for MSOP & SOIC packages. Updates to qualification status and Assembly site

